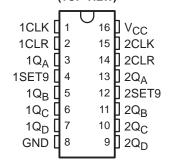
- Dual Versions of the SN54LS90 and SN74LS90 Counters
- Individual Clock, Direct Clear, and Set-to-9
 Inputs for Each Decade Counter
- Dual Counters Can Significantly Improve System Densities as Package Count Can Be Reduced by 50%
- Maximum Count Frequency of 25 MHz . . . 35 MHz Typical
- Buffered Outputs Reduce Possibility of Collector Commutation
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) DIPs

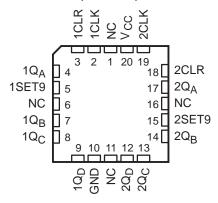
description

Each of these monolithic circuits contains eight master-slave flip-flops and additional gating to implement two individual 4-bit decade counters in a single package. Each decade counter has individual clock (1CLK, 2CLK), clear (1CLR, 2CLR), and set-to-9 (1SET9, 2SET9) inputs. BCD count sequences of any length up to divide-by-100 can be implemented with a single 'LS490 device. Buffering on each output is provided to significantly reduce susceptibility to collector commutation. All inputs are diode clamped to reduce the effects of line ringing. The counters have parallel outputs from each counter stage so that submultiples of the input count frequency are available for system timing signals.

SN54LS490 . . . J OR W PACKAGE SN74LS490 . . . D OR N PACKAGE (TOP VIEW)



SN54LS490 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54LS490 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LS490 is characterized for use in industrial systems operating from 0°C to 70°C.

CLEAR/SET-TO-9 FUNCTION TABLE (each counter)

INP	UTS		OUTI	PUTS	
CLR	SET9	QA	Q_{B}	QC	Q_{D}
Н	L	L	L	L	L
L	Н	Н	L	L	Н
L	L		Co	unt	



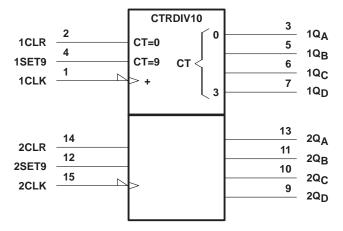
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



BCD COUNT SEQUENCE (each counter)

COUNT		OUT	PUTS	
COONT	Q_{D}	QC	Q_{B}	Q_{A}
0	L	L	L	L
1	L	L	L	н
2	L	L	Н	L
3	L	L	Н	Н
4	L	Н	L	L
5	L	Н	L	Н
6	L	Н	Н	L
7	L	Н	Н	Н
8	Н	L	L	L
9	Н	L	L	Н

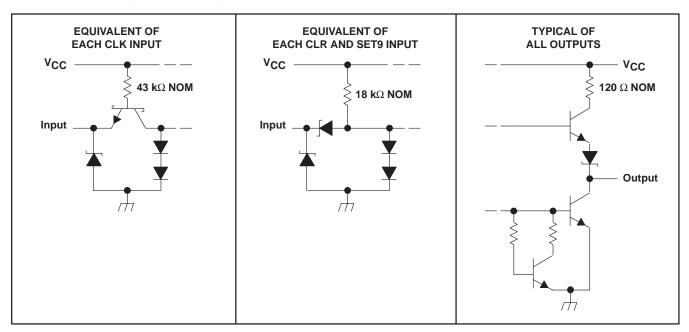
logic symbol†



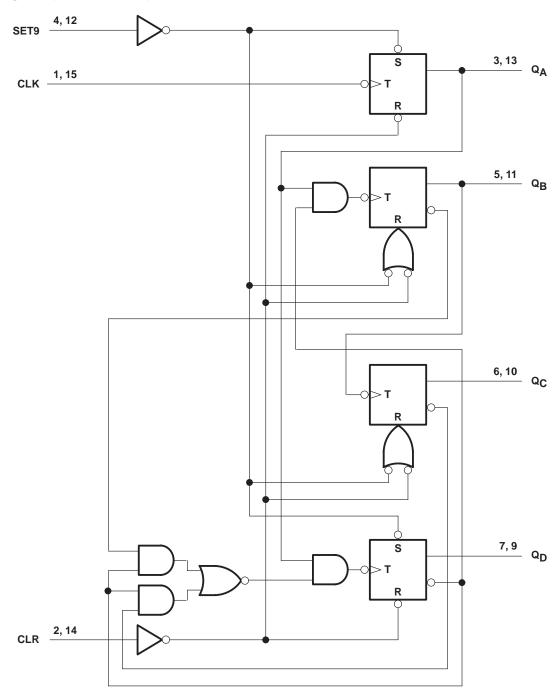
 $[\]dagger$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, and W packages.



schematics of inputs and outputs



logic diagram (each counter)



Pin numbers shown are for the D, J, N, and W packages.



SDLS125A - OCTOBER 1976 - REVISED JULY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	0.5 V to 7 V
Clear and set-to-9 voltage	
Clock input voltage	
Package thermal impedance, θ _{JA} (see Note 2): D package	
N package	
Storage temperature range, T _{sto}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Voltage values are with respect to network ground terminal.

recommended operating conditions

		SI	N54LS49	0	SI	N74LS49	0	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
ІОН	High-level output current			-400			-400	μΑ
loL	Low-level output current			4			8	mA
fcount	Count frequency	0		25	0		25	MHz
t _W	Pulse width (any input)	20			20			ns
t _{su}	Clear or set-to-9 inactive-state setup time	25↓‡			25↓‡			ns
T _A	Operating free-air temperature	-55		125	0		70	°C

[‡]The arrow (\$\psi\$) indicates that the falling edge of the clock pulse is used for reference.

^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

SDLS125A - OCTOBER 1976 - REVISED JULY 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS [†]		SI	SN74LS490		SI	174LS49	0	UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
VIH	High-level input v	oltage			2			2			V
VIL	Low-level input vo	oltage					0.7			0.8	V
VIK	Input clamp volta	ge	$V_{CC} = MIN,$	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
V _{OH} High-level output voltage		V _{CC} = MIN, V _{IH}	= 2 V,	2.5	3.4		2.7	3.4		V	
		voltogo	V _{CC} = MIN,	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
VOL	V _{OL} Low-level output voltage		V _{IH} = 2 V, V _{IL} = V _{IL} max	I _{OL} = 8 mA					0.35	0.5	V
1.	Input current	CLR, SET9	$V_{CC} = MAX$,	V _I = 7 V			0.1			0.1	mA
11	at maximum input voltage CLK		V _{CC} = MAX,	V _I = 5.5 V			0.2			0.2	IIIA
1	High-level	CLR, SET9	V MAY	V _I = 2.7 V			20			20	μА
lін	input current CLK		$V_{CC} = MAX,$	V = 2.7 V			100			100	μΑ
1	I _{IL} Low-level CLR, SET9 input current CLK		V MAAY	V _I = 0.4 V			-0.4			-0.4	mA
I IIL			$V_{CC} = MAX,$	v = 0.4 v			-1.6			-1.6	IIIA
los§	OS [§] Short-circuit output current V _{CC}		$V_{CC} = MAX$		-20		-100	-20		-100	mA
ICC			$V_{CC} = MAX$,	See Note 3		15	26		15	26	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figures 1 and 2)

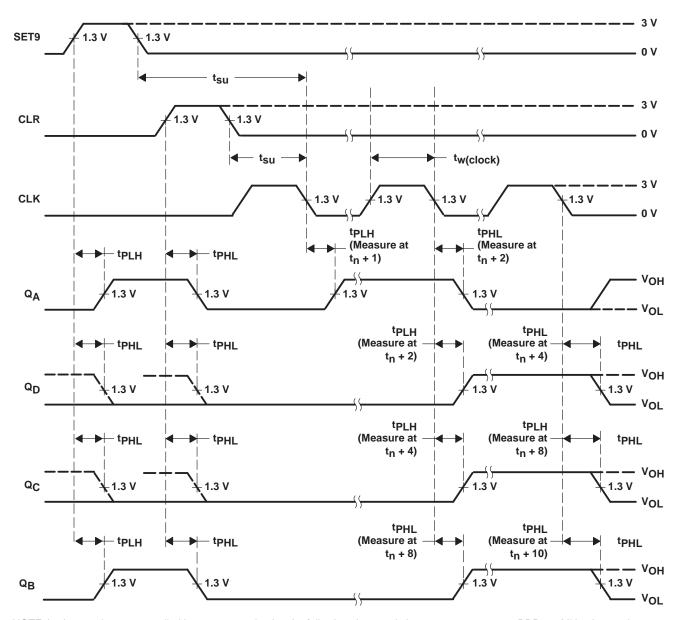
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}	CLK	Q_A	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega$	25	35		MHz
^t PLH	CLK	0.	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega$		12	20	ns
^t PHL	CLK	Q _A	OL = 15 pr, KL = 2 ks2		13	20	
^t PLH	CLK	05.05	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega$		24	39	
^t PHL	CLK	Q _{B,} Q _D	OL = 15 pr, KL = 2 ks2		26	39	
t _{PLH}	CLK	00	$C_{\parallel} = 15 \text{ pF}, R_{\parallel} = 2 \text{ k}\Omega$		32	54	ns
^t PHL	OLK	QC	OL = 13 pr, KL = 2 KS2		36	54	115
^t PHL	CLR	Any	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega$		24	39	ns
t _{PLH}	SET9	Q_{A, Q_D}	C: -15 pE		24	39	no
^t PHL	3E19	$Q_{B_{I}}Q_{C}$	$C_L = 15 \text{ pF}, R_L = 2 \text{ k}\Omega$		20	36	ns

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

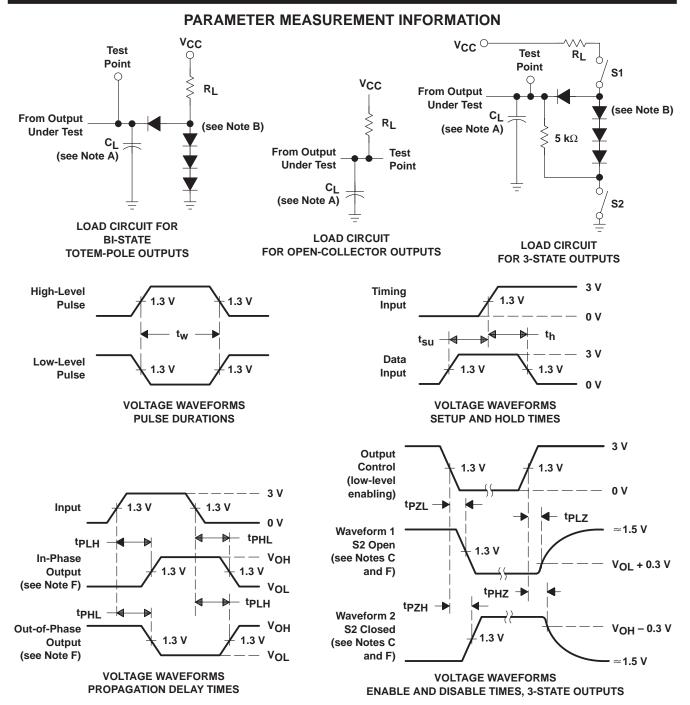
NOTE 3: ICC is measured with all outputs open, both CLR inputs grounded following momentary connection to 4.5 V, and all other inputs grounded.

PARAMETER MEASUREMENT INFORMATION



NOTE A: Input pulses are supplied by a generator having the following characteristics: $t_{\Gamma} \le 15$ ns, $t_{f} \le 6$ ns, PRR ≤ 1 MHz, duty cycle = 50%, $Z_{O} \approx 50~\Omega$.

Figure 1. Voltage Waveforms



- NOTES: A. C_I includes probe and jig capacitance.
 - B. All diodes are 1N3064 or equivalent.
 - C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - D. In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily.
 - E. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O \approx 50~\Omega$, $t_f \leq$ 15 ns, $t_f \leq$ 6 ns.
 - F. S1 and S2 are closed for tpLH, tpHL, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
 - G. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS490N	OBSOLETE	PDIP	N	16	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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